

# Aluminium Press Pack

## Aluminium

Mersen aluminium Press Pack provides the maximum thermal performance in employing proprietary channeling techniques to optimize coolant velocity at low pressure drop while providing uniform temperature across the mounting surface for semiconductor reliability.

It is an effective and reliable solution. Liquid cooled systems work perfectly for power electronics components, especially when installed in a confined space.

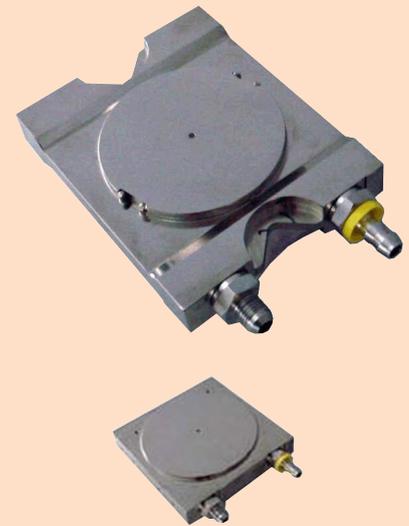
Mersen is expert in vacuum brazing technology which ensure maximum reliability: guaranteed water tightness with no leak, robustness, no corrosion and excellent thermal performance. Result: a product sure to last decades!

### Features Benefits

- 100% aluminium (alloy)
- High thermal performance (cost cutting with no derating of power module)
- Low pressure drop compared to similar product
- Homogeneous temperature distribution below semiconductor
- Very high pressure withstanding guarantee
- Perfect water tightness with no risk of leak
- All cold plates systematically pressure tested at 100%
- Vacuum brazing technology means no corrosion: flux free!
- Long life time: >20 years guaranteed
- Options:
  - Surface coating
  - Tab for electrical connections
  - Fitting as per customer requirements

### Applications

- Cooling of any size of press pack semiconductor



### Standards

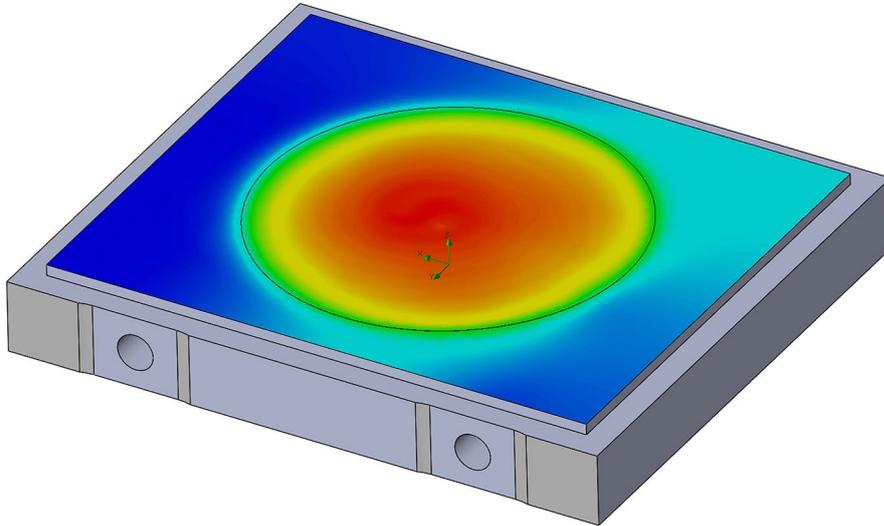
Vacuum-brazing technology  
RoHS compliant



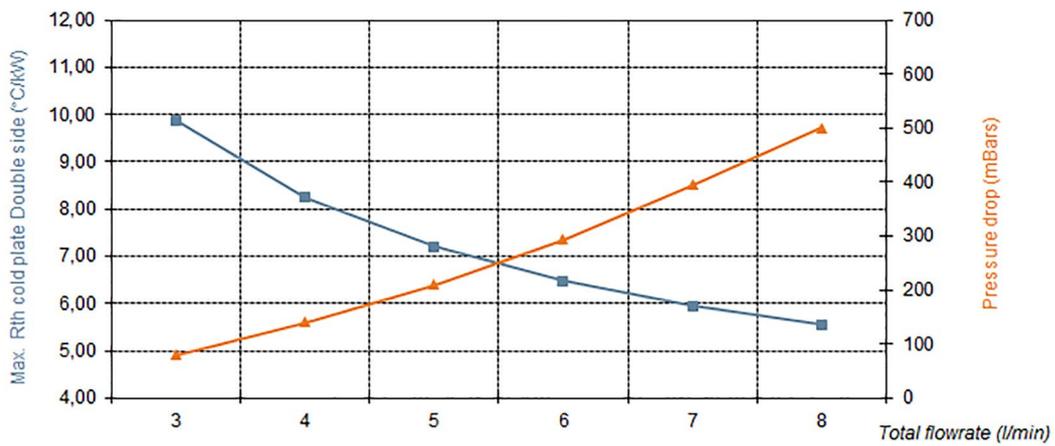
# Aluminium Press Pack

## Thermal and Hydraulic performances

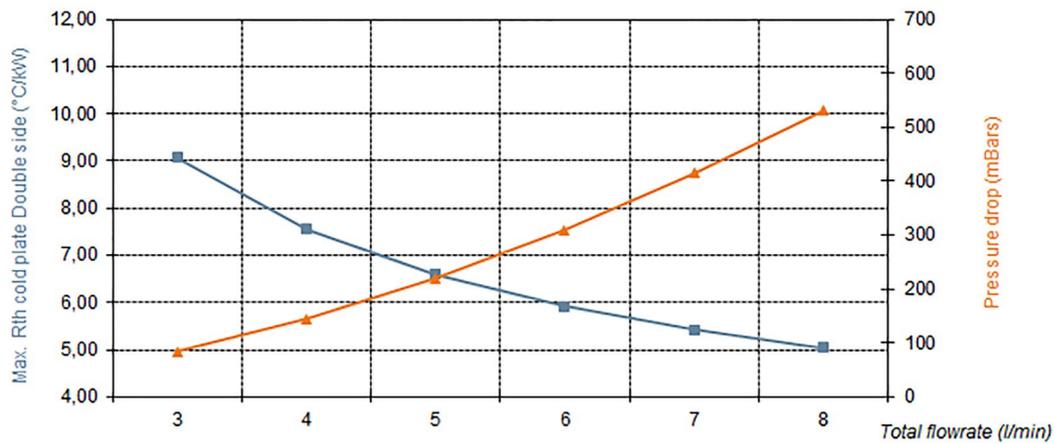
Perfect homogeneous temperature distribution below semiconductor for high reliability



Semiconductor contact surface diameter: 85mm



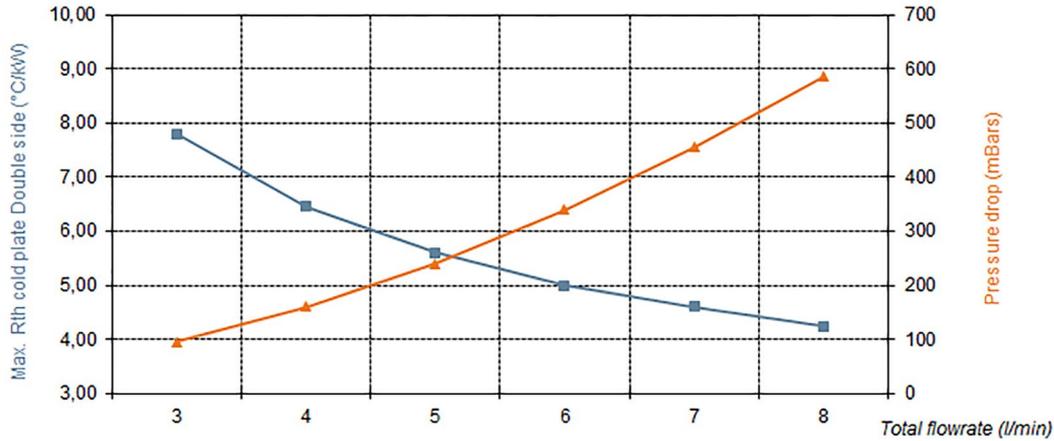
Semiconductor contact surface diameter: 90mm



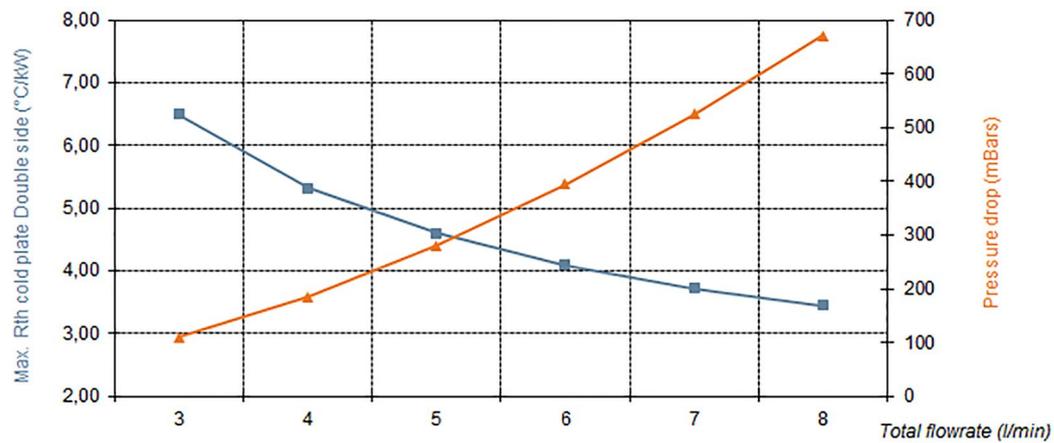
# Aluminium Press Pack

## Thermal and Hydraulic performances

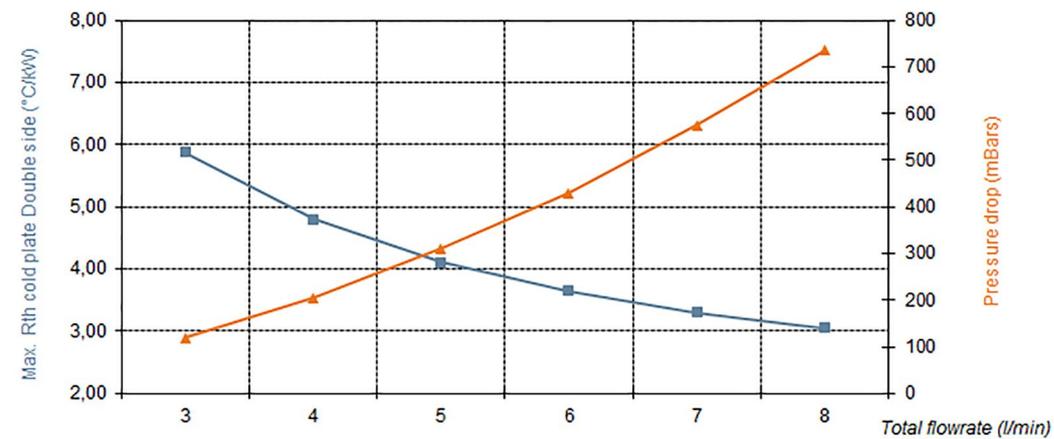
Semiconductor contact surface diameter: 100mm



Semiconductor contact surface diameter: 115mm



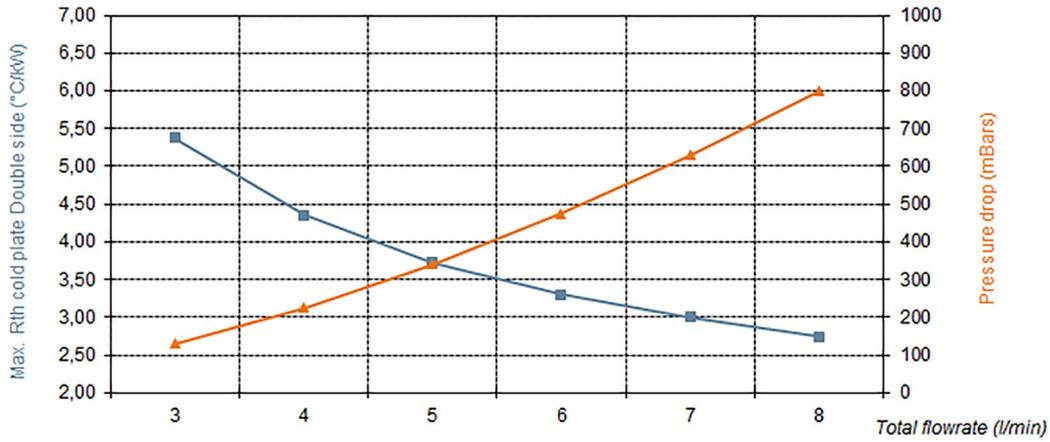
Semiconductor contact surface diameter: 125mm



# Aluminium Press Pack

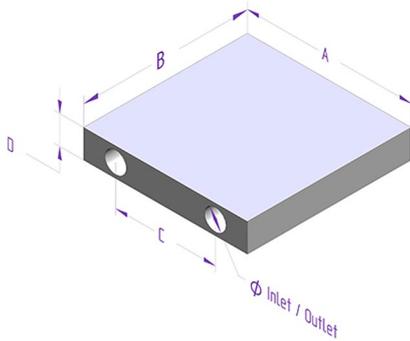
## Thermal and Hydraulic performances

Semiconductor contact surface diameter: 135mm



## Dimensions

Contact view



Ø Component	A	B	C	D
Ø85	110	110	70	Ø Inlet / Outlet + 5mm
Ø90	115	115	70	Ø Inlet / Outlet + 5mm
Ø100	125	125	80	Ø Inlet / Outlet + 5mm
Ø115	140	140	80	Ø Inlet / Outlet + 5mm
Ø125	150	150	100	Ø Inlet / Outlet + 5mm
Ø135	160	160	100	Ø Inlet / Outlet + 5mm